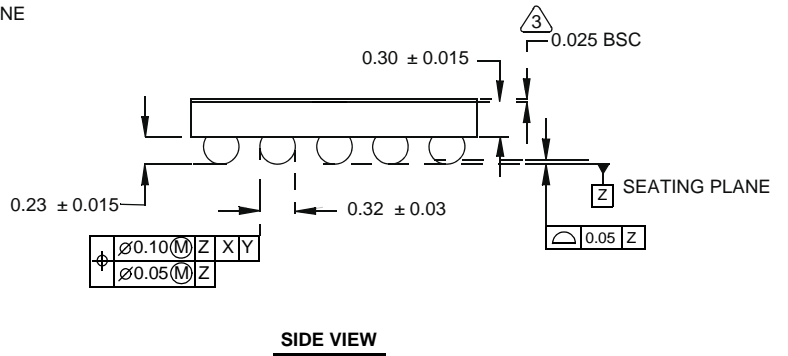
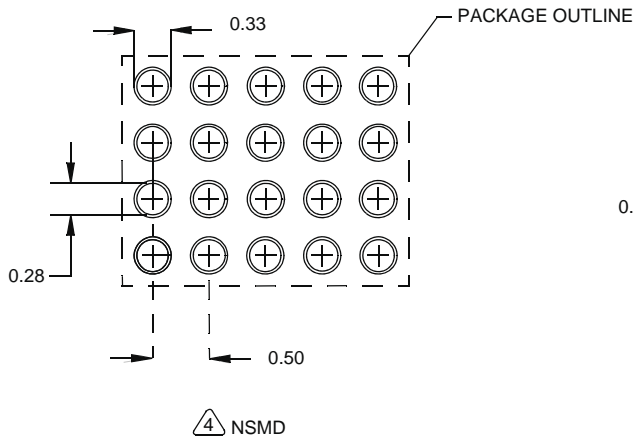
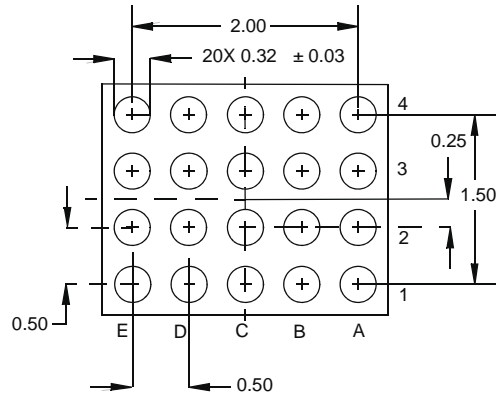
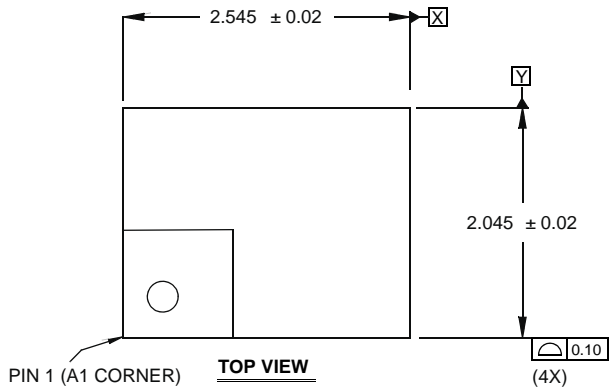


Package Outline Drawing

W4x5.20

4x5 Array 20 Ball Wafer Level Chip Scale Package (WLCSP)
Rev 1 8/09



NOTES:

1. Dimensions are in millimeters.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994, and JESD 95-1 SPP-10.
3. Back side coat 0.25mm thick applied to CSP package top.
4. NSMD refers to non-solder mask defined pad design per Intersil tech brief www.intersil.com/data/tb/TB451.pdf